### TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT SILICON GATE CMOS

#### 524.288-WORD BY 8-BIT CMOS STATIC RAM

#### **DESCRIPTION**

The TC55V8512J/FT is a 4,194,304-bit high-speed static random access memory (SRAM) organized as 524,288 words by 8 bits. Fabricated using CMOS technology and advanced circuit techniques to provide high speed, it operates from a single 3.3 V power supply. Chip enable  $(\overline{\text{CE}})$  can be used to place the device in a low-power mode, and output enable  $(\overline{\text{OE}})$  provides fast memory access. This device is well suited to cache memory applications where high-speed access and high-speed storage are required. All inputs and outputs are directly LVTTL compatible. The TC55V8512J/FT is available in plastic 36-pin SOJ and 44-pin TSOP with 400mil width for high density surface assembly.

### **FEATURES**

- Fast access time (the following are maximum values) TC55V8512J/FT-12:12 ns TC55V8512J/FT-15:15 ns
- Low-power dissipation (the following are maximum values)

Cycle Time	12	15	20	25	ns
Operation (max)	170	140	130	110	mA

Standby: 4 mA (both devices)

- Single power supply voltage of  $3.3 \text{ V} \pm 0.3 \text{ V}$
- Fully static operation
- · All inputs and outputs are LVTTL compatible
- Output buffer control using  $\overline{OE}$
- Package:

SOJ36-P-400-1.27 (J)	(Weight: 1.35 g typ)
TSOP II44-P-400-0.80 (FT)	(Weight: 0.45 g typ)

### **PIN ASSIGNMENT** (TOP VIEW)

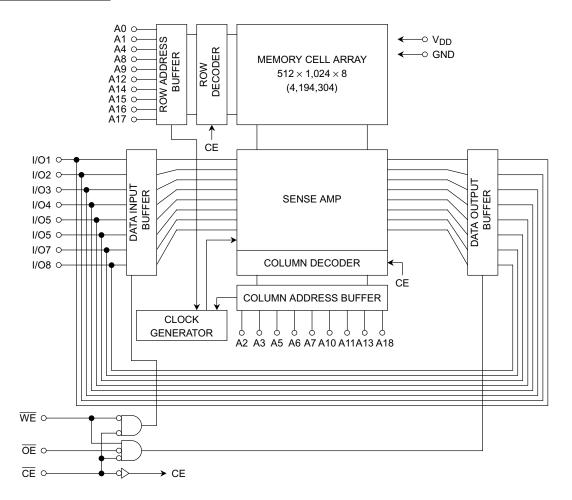
### 36 PIN SOJ 44 PIN TSOP

A17	36   NC 35   A4 34   A5 33   A6 32   A7 31   OE 30   I/O8 29   I/O7 28   GND 26   I/O6 25   I/O6 25   I/O6 24   A8 23   A9 22   A10 21   A11 20   A12 19   NU	NC	44 NC 43 NC 42 NC 41 A4 40 A5 39 A6 38 A7 37 OE 36 Vor 34 GND 33 Vor 32 Vor 32 Vor 34 NC 41 A4 40 A5 A5 A7
(TC55V85	12J)	(TC	55V8512FT)

### **PIN NAMES**

A0 to A18	Address Inputs
I/O1 to I/O8	Data Inputs/Outputs
CE	Chip Enable Input
WE	Write Enable Input
ŌĒ	Output Enable Input
$V_{DD}$	Power (+3.3 V)
GND	Ground
NC	No Connection
NU	Not Usable (Input)

### **BLOCK DIAGRAM**



### **MAXIMUM RATINGS**

SYMBOL	RATING	VALUE	UNIT
$V_{DD}$	Power Supply Voltage	-0.5 to 4.6	V
V <sub>IN</sub>	Input Terminal Voltage	−0.5* to 4.6	V
V <sub>I/O</sub>	Input/Output Terminal Voltage	-0.5* to V <sub>DD</sub> + 0.5**	V
P <sub>D</sub>	Power Dissipation	1.4	W
T <sub>solder</sub>	Soldering Temperature (10s)	260	°C
T <sub>stg</sub>	Storage Temperature	–65 to 150	°C
T <sub>opr</sub>	Operating Temperature	-10 to 85	°C

<sup>\*: -1.5</sup> V with a pulse width of 20% t<sub>RC</sub> min (4 ns max)

### DC RECOMMENDED OPERATING CONDITIONS (Ta = 0° to 70°C)

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
$V_{DD}$	Power Supply Voltage	3.0	3.3	3.6	V
V <sub>IH</sub>	Input High Voltage	2.0	_	V <sub>DD</sub> + 0.3**	V
V <sub>IL</sub>	Input Low Voltage	-0.3*	_	0.8	V

<sup>\*: –1.0</sup> V with a pulse width of 20%  $^{\bullet}\,t_{RC}$  min (4 ns max)

<sup>\*\*:</sup>  $V_{DD}$  + 1.5 V with a pulse width of 20%  $\cdot$   $t_{RC}$  min (4 ns max)

<sup>\*\*:</sup>  $V_{DD}$  + 1.0 V with a pulse width of 20%  $\cdot$   $t_{RC}$  min (4 ns max)



## DC CHARACTERISTICS (Ta = $0^{\circ}$ to $70^{\circ}$ C, $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$ )

SYMBOL	PARAMETER	TEST CONDITION		MIN	TYP	MAX	UNIT
I <sub>IL</sub>	Input Leakage Current (Except NU pin)	V <sub>IN</sub> = 0 to V <sub>DD</sub>		-1	_	1	μΑ
I <sub>LO</sub>	Output Leakage Current	$\overline{CE} = V_{IH} \text{ or } \overline{WE} = V_{IL} \text{ or } \overline{OE} = V_{IH},$ $V_{OUT} = 0 \text{ to } V_{DD}$		-1	_	1	μΑ
	Input Current	V <sub>IN</sub> = 0 to 0.8 V		-1	_	20	4
lı (NU)	(NU pin)	V <sub>IN</sub> = 0 to 0.2 V		-1	_	1	μΑ
.,	Outrant High Walters	$I_{OH} = -2 \text{ mA}$		2.4	_	_	
V <sub>OH</sub>	Output High Voltage	$I_{OH} = -100 \mu\text{A}$		V <sub>DD</sub> – 0.2	_	_	V
.,	Out = 1 = 1   1   1   1   1   1   1   1   1	I <sub>OL</sub> = 2 mA		_	_	0.4	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 100 μA		_	_	0.2	
			t <sub>cycle</sub> = 12 ns	_	_	170	
	0	$\overline{CE} = V_{IL}, I_{OUT} = 0 \text{ mA},$	t <sub>cycle</sub> = 15 ns	_	_	140	0
IDDO	Operating Current	$\overline{OE} = V_{IH},$ Other Input = $V_{IH}/V_{IL}$	t <sub>cycle</sub> = 20 ns	_	_	130	mA
		outor input = VIII/VIL	t <sub>cycle</sub> = 25 ns	_	_	110	
I <sub>DDS1</sub>	Ot	CE = V <sub>IH</sub> , Other Input = V <sub>IH</sub> or V <sub>IL</sub>		_	_	50	0
I <sub>DDS2</sub>	Standby Current	$\overline{CE} = V_{DD} - 0.2 \text{ V}$ , Other Input = $V_{DD} - 0.2 \text{ V}$	0.2 V or 0.2 V	_	_	4	mA

## **CAPACITANCE** (Ta = 25°C, f = 1.0 MHz)

SYMBOL	PARAMETER	TEST CONDITION	MAX	UNIT
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = GND	6	pF
C <sub>I/O</sub>	Input/Output Capacitance	$V_{I/O} = GND$	8	pF

Note: This parameter is periodically sampled and is not 100% tested.

## **OPERATING MODE**

MODE	CE	ŌĒ	WE	I/O1 to I/O8	POWER
Read	L	L	Н	Output	I <sub>DDO</sub>
Write	L	*	L	Input	I <sub>DDO</sub>
Outputs Disable	L	Н	Н	High Impedance	I <sub>DDO</sub>
Standby	Н	*	*	High Impedance	I <sub>DDS</sub>

<sup>\* :</sup> Don't care

Note: The NU pin must be left unconnected or tied to GND or a voltage level of less than 0.8 V. You must not apply a voltage of more than 0.8 V to the NU.



## <u>AC CHARACTERISTICS</u> (Ta = $0^{\circ}$ to $70^{\circ}$ C <sup>(See Note 1)</sup>, $V_{DD} = 3.3 \text{ V} \pm 0.3 \text{ V}$ )

## **READ CYCLE**

			TC55V8512J/FT			
SYMBOL	PARAMETER		12		15	UNIT
		MIN	MAX	MIN	MAX	
t <sub>RC</sub>	Read Cycle Time	12	_	15	_	
t <sub>ACC</sub>	Address Access Time	_	12	_	15	
t <sub>CO</sub>	Chip Enable Access Time	_	12	_	15	
toE	Output Enable Access Time	_	6	_	8	
tон	Output Data Hold Time from Address Change	3	_	4	_	ns
t <sub>COE</sub>	Output Enable Time from Chip Enable	3	_	4	_	
toee	Output Enable Time from Output Enable	1	_	1	_	
t <sub>COD</sub>	Output Disable Time from Chip Enable	_	7	_	8	
t <sub>ODO</sub>	Output Disable Time from Output Enable	_	7	_	8	

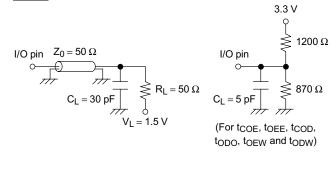
### WRITE CYCLE

			TC55V8	3512J/FT		
SYMBOL	PARAMETER		-12		-15	
		MIN	MAX	MIN	MAX	
twc	Write Cycle Time	12	_	15	_	
t <sub>WP</sub>	Write Pulse Width	8	_	9	_	
t <sub>CW</sub>	Chip Enable to End of Write	10	_	12	_	
t <sub>AW</sub>	Address Valid to End of Write	10	_	12	_	
t <sub>AS</sub>	Address Setup Time	0	_	0	_	ns
t <sub>WR</sub>	Write Recovery Time	0	_	0	_	115
t <sub>DS</sub>	Data Setup Time	7	_	8	_	
t <sub>DH</sub>	Data Hold Time	0	_	0	_	
toew	Output Enable Time from Write Enable	1	_	1	_	
t <sub>ODW</sub>	Output Disable Time from Write Enable		7		8	

## **AC TEST CONDITIONS**

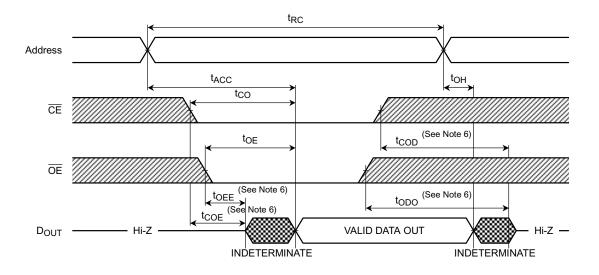
PARAMETER	TEST CONDITION
Input Pulse Level	3.0 V/ 0.0 V
Input Pulse Rise and Fall Time	2 ns
Input Timing Measurement Reference Level	1.5 V
Output Timing Measurement Reference Level	1.5 V
Output Load	Fig.1

### Fig.1

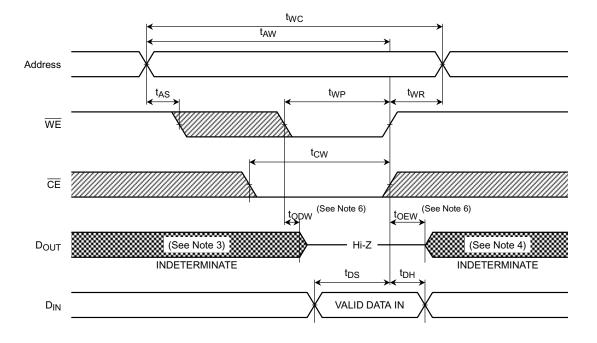


## **TIMING DIAGRAMS**

# READ CYCLE (See Note 2)

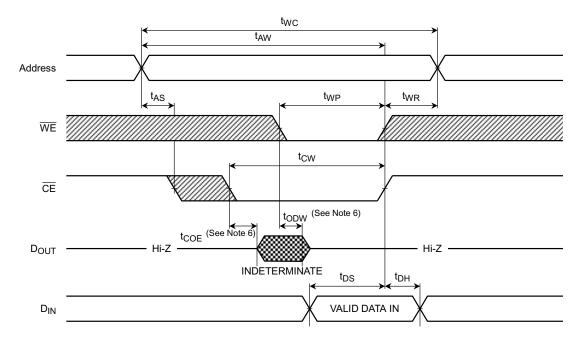


## WRITE CYCLE 1 (WE CONTROLLED) (See Note 5)



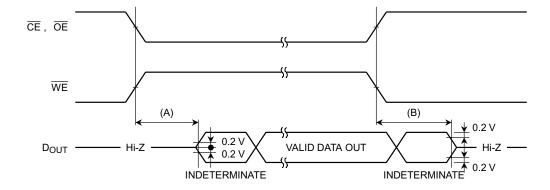


## WRITE CYCLE 2 (CE CONTROLLED) (See Note 5)

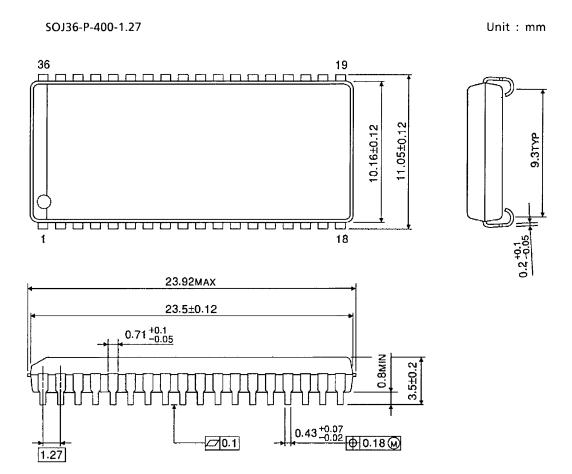


Note:

- (1) Operating temperature (Ta) is guaranteed for transverse air flow exceeding 400 linear feet per minute.
- (2) WE remains HIGH for the Read Cycle.
- (3) If  $\overline{\text{CE}}$  goes LOW coincident with or after  $\overline{\text{WE}}$  goes LOW, the outputs will remain at high impedance.
- (4) If  $\overline{\text{CE}}$  goes HIGH coincident with or before  $\overline{\text{WE}}$  goes HIGH, the outputs will remain at high impedance.
- (5) If  $\overline{OE}$  is HIGH during the write cycle, the outputs will remain at high impedance.
- (6) The parameters specified below are measured using the load shown in Fig.1.
  - (A) tcoe, toee, toew ..... Output Enable Time
  - (B) tCOD, tODO, tODW ..... Output Disable Time



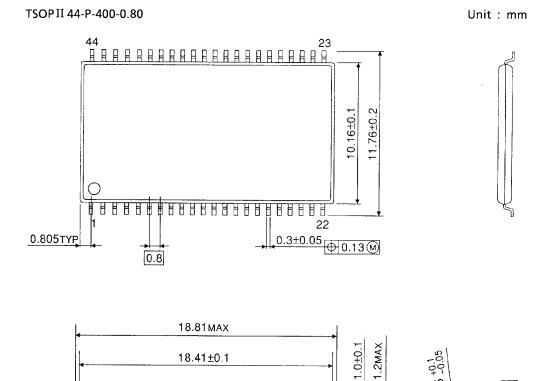
## **PACKAGE DIMENSIONS**



Weight: 1.35 g (typ)

 $0.5 \pm 0.1$ 

## **PACKAGE DIMENSIONS**



0.1±0.05

ZZ 0.1

Weight: 0.45 g (typ)

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Handbook" etc..

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